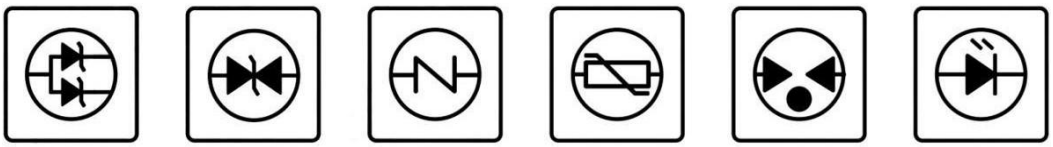
MSKSEMI 美森科
SEMICONDUCTOR



SS32-MS THRU SS310-MS

Product specification

MSKSEMI
SEMICONDUCTOR

SS32-MS THRU SS310-MS

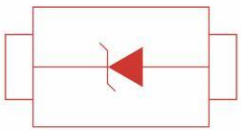
FEATURES

- The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- For surface mounted applications
- Low reverse leakage
- Built-in strain relief,ideal for automated placement
- High forward surge current capability
- High temperature soldering guaranteed: 250 C/10 seconds at terminals

MECHANICAL DATA

- **Case**: DO-214AC
- **Terminals**: leads solderable per MIL-STD-750,
- Method 2026
- **Polarity**: Color band denotes cathode end
- **Mounting Position**: Any
- **Weight**:0.002 ounce, 0.07 grams

Reference News

PACKAGE OUTLINE	PIN CONFIGURATION
	
SMA(DO-214AC)	

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25℃ ambient temperature unless otherwise specified.

Single phase half-wave 60Hz,resistive or inductive load,for capacitive load current derate by 20%

	SYMBOLS	SS32-MS	SS34-MS	SS36-MS	SS310-MS	UNITS
Maximum repetitive peak reverse voltage	V_{RRM}	20	40	60	100	VOLTS
Maximum RMS voltage	V_{RMS}	14	28	42	70	VOLTS
Maximum DC blocking voltage	V_{DC}	20	40	60	100	VOLTS
Maximum average forward rectified current at T_L(see fig.1)	$I_{(AV)}$	3.0				Amps
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	100.0				Amps
Maximum instantaneous forward voltage at 3.0A	V_F	0.55		0.70	0.85	Volts
Maximum DC reverse current at rated DC blocking voltage T_A=25℃	I_R	0.5				mA
Maximum DC reverse current at rated DC blocking voltage T_A=100℃	I_R	20			10	mA
Typical junction capacitance (NOTE 1)	C_J	500		300		pF
Typical thermal resistance (NOTE 2)	$R_{\theta JA}$	55.0				C/W
Operating junction temperature range	T_J,	-50 to +125			-50 to +150	℃
Storage temperature range	T_{STG}	-50 to +150				℃

Note:1.Measured at 1MHz and applied reverse voltage of 4.0VD.C.

2.P.C.B. mounted with 0.2x0.2"(5.0x5.0mm) copper pad areas

FIG. 1- FORWARD CURRENT DERATING CURVE

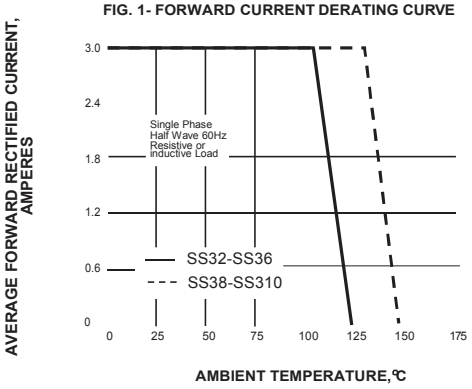


FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

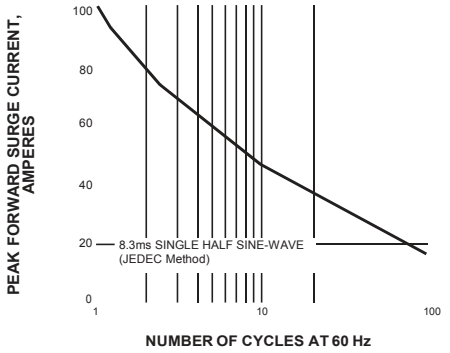


FIG. 3-TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

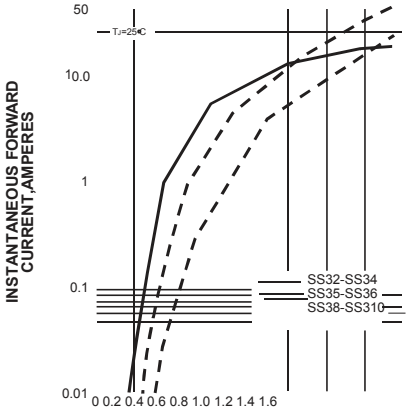


FIG. 4-TYPICAL REVERSE CHARACTERISTICS

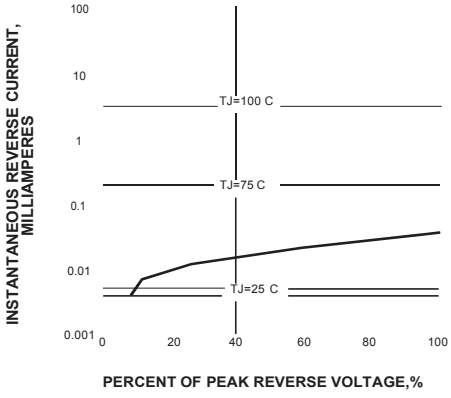


FIG. 5-TYPICAL JUNCTION CAPACITANCE

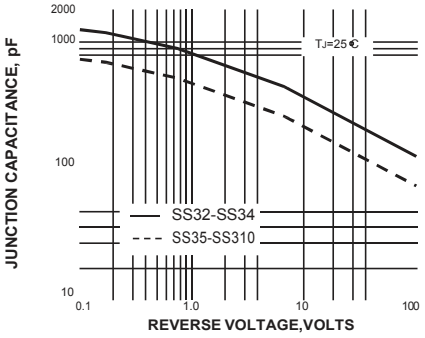
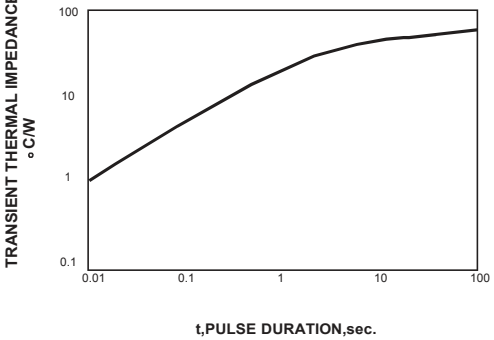
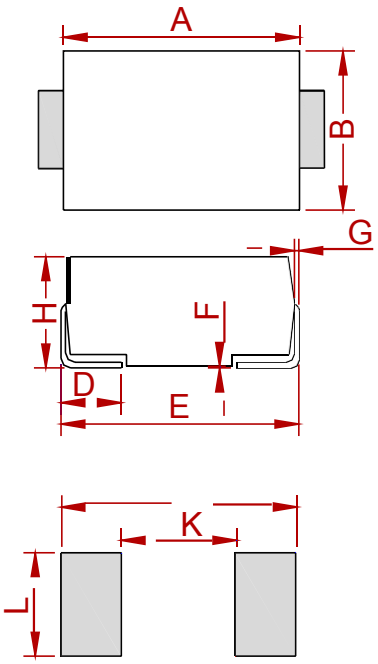


FIG. 6-TYPICAL TRANSIENTTHERMALIMPEDANCE



PACKAGE ECHANICAL DATA



DO-214AC (SMA)

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.25	4.65	0.167	0.183
B	2.50	2.90	0.098	0.114
C	1.35	1.65	0.053	0.065
D	0.76	1.52	0.030	0.060
E	4.93	5.28	0.194	0.208
F	0.051	0.203	0.002	0.008
G	0.15	0.31	0.006	0.012
H	1.98	2.41	0.078	0.095
J	6.50		0.256	
K		2.30		0.090
L	1.70		0.067	

REEL SPECIFICATION

P/N	PKG	QTY
SS32-MS THRU SS310-MS	SMA	2000

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